Consume. Collaborate. Contribute.

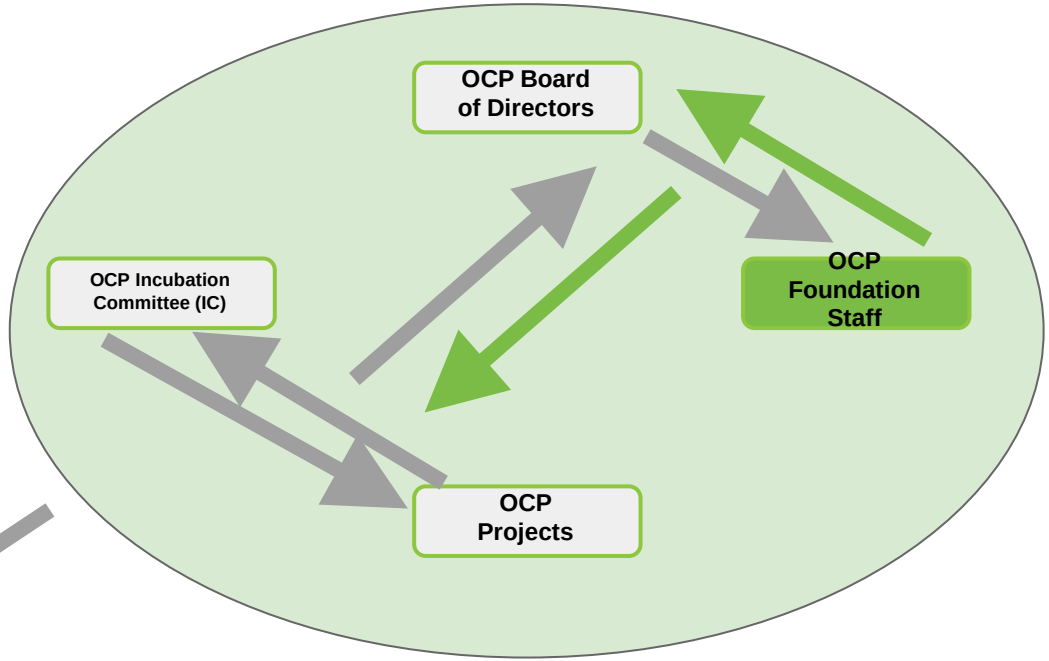
Keys to success in the OCP Community

Communication

Communication is important at all levels of the OCP Community.

In order to make OCP easier to **consume** we must **collaborate** and **contribute**.

Open communication (collaboration) is **KEY** to driving OCP adoption (consume) and innovation (contribution).



Community empowers people. We want to the OCP Community to be empowered to drive open hardware into various industries such as Telco, Finanical, Enterprise and more. However, in order to do so OCP Members have to participate in the projects and be part of the team.

OCP Foundation Structure

OCP Incubation Committee

* **Chair:** Andy Bechtolsheim
* **Vice Chair** - Amir Michael (OCP Co-founder)
* Aaron Sullivan (Rackspace)
* William “Bill” Carter (Intel)
* Chilung Wang (ITRI)
* Kushagra Vaid (Microsoft)
* Eran Tal (Facebook)
* Conor Malone (Hyve Solutions)
* Bob Ogrey (AMD)
* Lakshmi Mandyam (ARM)
* Open Telco Seat (TBD)

OCP Foundation Board

* **Chairman/President** - Jason Taylor (Facebook)
* Don Duet, (Goldman Sachs)
* Jason Waxman (Intel)
* Bill Laing (Microsoft)
* Mark Roenigk (Rackspace)
* Andy Bechtolsheim (Individual)
* Frank Frankovsky (Individual)
* Rocky Bullock (non-voting)

Corey Bell and Rocky Bullock
Co-Chief Executive Officer

Amber Graner
Operations Director and Community Manager

Steve Helvie
VP Chanel Development

Bill Carter
Chief Technology Officer

Sales Support Team**
(Currently Staffed by Facebook)

Marketing & Events**
(Currently Staffed by Facebook)

Michael Schill
Community Support Specialist

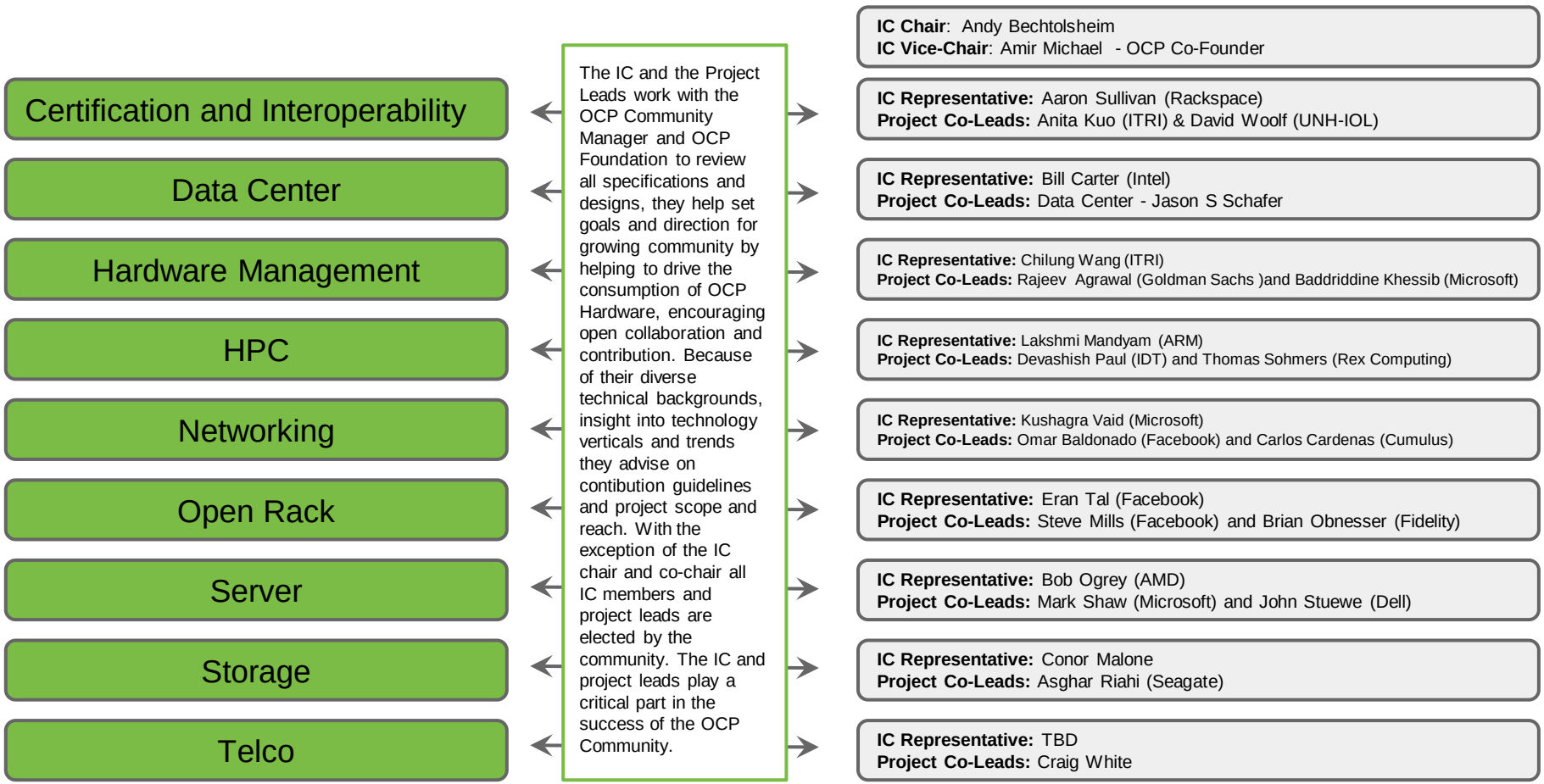
Stephanie Loayza
Events Manager

OCP Projects

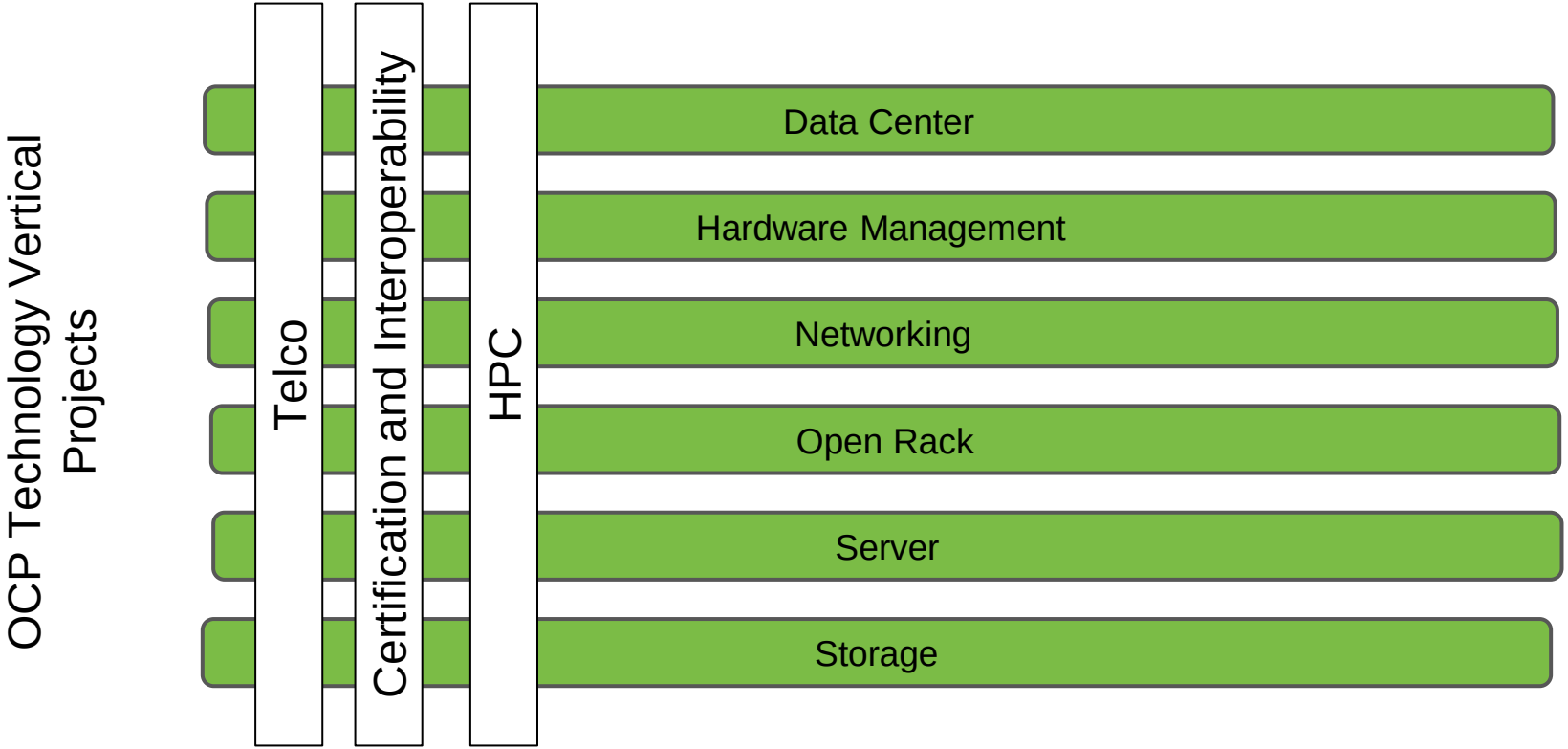
Certification & Interoperability	Data Center	Hardware Management	HPC	Networking	Open Rack	Server	Storage	Telco
David Woolf (UNH) Anita Kuo (ITRI)	Jason S. Schafer -	Rajeev Agrawala Badriddine Khessib	Devashish Paul Thomas Sohmers	Omar Baldonado Carlos Cardenas	Steve Mills Brian Obnesser	Mark Shaw John Stuewe	Asghar Riahi	Craig White
Project Co-Leads	Project Lead	Project Co-Leads	Project Co-Leads	Project Co-Leads	Project Co-Leads	Project Co-Leads	Project Lead	Project Lead

*IC Chair and Vice Chair are Board appointed - all other seats will be community elected in 2014 **While currently staffed by Facebook, all board members companies may give staffing resources to the Foundaton,

OCP IC Members and Project Leads



OCP Projects that cross/interact with all Technology Verticals



How to participate?

There are many ways to publicly participate in the OCP Community.

Join the mailing list and add to the conversation and help drive the focus of the projects.
(http://lists.opencompute.org/mailman/listinfo)

Join the online project meetings and participate in the discussion and provide thought leadership.
(http://www.opencompute.org/participate/events/)

Participate in-person at the OCP Events - Summit, Engineering Workshops, OCP Days
(http://www.opencompute.org/participate/events/)

Participate in Industry events and represent your organization's interest in OCP (Let the Foundation know at least 2 weeks prior so we can promote your organization)

Become an OCP Member and participate in the OCP Projects.

Contribute Hardware specifications and designs.

Run for an OCP Leadership Position (Project Lead, IC Member, Regional Community Leader)

How to be a successful participant in an Open Community?

1. Participation gives you significantly better insight and awareness into the community, its processes, specifications and who actively engaged.

2. By attending OCP events and engaging online, you place yourself and your organization in a better position to understand and leverage the solutions that are already available.

3. You will know where and how to find those specifications and more, and have a better sense of how you can leverage that knowledge to achieve both your individual and your organizations goals.

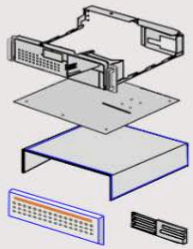
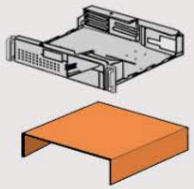
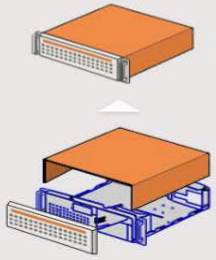
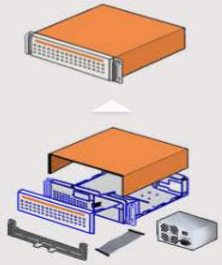
4. Once you have this knowledge and experience then you and your organization become capable of executing faster and more efficiently than other organizations who don't engage.

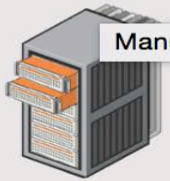
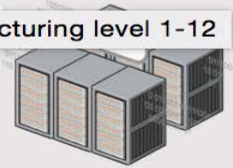
5. Another great advantage of participation is that, when you need it, you will probably get better help – and faster. You have merit, people know you and have build a relationship with you. It's human nature to help want to help those you know and trust. (Remember Transparency and Open Communication are just two ways to participate and build that trust.)

6. One of the most important benefits of participanting in the OCP community is your ability to drive innovation and enhance the hardware/software you rely on. While you can work with a vendor and make changes and drive innovations for your organization, it's better for the industry and Data Center Ecosystem as a whole if you consume, collaborate and contribute through the OCP Community, so everyone can help make the hardware better and the ecosystem stronger.

Current Solution Providers

MANUFACTURING LEVEL

Level 1	Level 2	Level 3	Level 4	Level 5	Level 6
Parts manufacturing - this includes non-painted parts and molding parts on the component level.	Piece Parts Sub Assembly - some level of assembly.	Metals and plastics are integrated together and shipped as a case (i.e. chassis).	Metals and Plastics + PSU and/or Flat Cable and/or Backplane are shipped as a kit or bag.	All enclosure parts from Level 4 attached, cables integrated, I/O tested	Integration of motherboard into chassis enclosure and power on test.
					Assembly & Test Motherboard

Level 7	Level 8	Level 9	Level 10	Level 11	Level 12
Integration of add-on cards into server barebone with ability to test.	Integration of hard drives into server barebone with ability to test.	Integration of CPU and memory into server barebone with ability to test.	Full assembly of server with full system and component level testing, OS/software integration, product kitted with user manual and other required documentation and delivered as a fully-integrated server solution.	Node-level assembly, testing, OS/software loading of all server nodes followed by rack cabinet assembly of nodes into racks with full cable networking (including switches), and tested as a working total solution at the rack or multi-rack level.	Rack to multi-rack level manufacturing featured in Level 11 including all networking with full software loading, validation and optimization. This may include but is not limited to cluster management, cloud OS (such as OpenStack) and networking software.
Assembly & Test Cards	Assembly & Test Cards	Assembly & Test CPU & Memory	Kitted in		

Manufacturing level 1-12

Graphic created by AMAX TOTAL COMPUTING SOLUTIONS

L6 = ODM L10 & L11 = SP

Thank you!

We are very excited to have each and every one of your organizations as members. The expertise that is around the table today is outstanding! The thought leadership you can bring to the OCP Community is remarkable and sets the stage for a great future. We look forward to your contributions and the future you help build for the OCP Telco Project, the OCP Community and the Telco Industry as a whole! And, I look forward to speaking with you all soon!

With gratitude,

~Amber

Consume. Collaborate. Contribute.